



SEMICONDUCTOR Small Signal Products

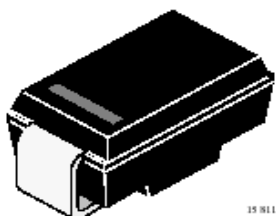
MATERIAL CONTENT LIST

PACKAGE
FAMILY:
DATE:
REVISION:

DO-214AC-M

24-Jul-2020

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15 0611

**HALOGEN
FREE**

**RoHS
COMPLIANT**



MATERIAL CONTENT					
Part	Material	CAS N°	weight mg	% of weight	ppm of total weight
Mold Compound	SiO ₂	60676-86-0	29.61	85.0%	406951
	Cured polymer (epoxy + phenolic resin reacted)		1.74	5.0%	23938
	Carbon Balck	1333-86-4	0.70	2.0%	9575
	Metal Hydroxide	21645-51-2	2.79	8.00%	38301
	TOTAL			34.83	
Lead frame	Cu	7440-50-8	33.3	99.7%	457735
	Sn	7440-31-5	0.1	0.3%	1375
	and / or traces of Mg, Ag, P, Fe				
TOTAL			33.4		
Terminal finish	Sn	7440-31-5	2.0	100.0%	26804
	TOTAL		2.0		
Die solder	Pb *)	7439-92-1	0.88	88.0%	12061
	Sn	7440-31-5	0.10	10.0%	1370
	Ag	7440-22-4	0.02	2.0%	275
	TOTAL		1.0		
Silicon	Si	7440-21-3	1.29	82.2%	17766
	SiO ₂	14808-60-7	0.036	2.3%	498
chip metallization	Ag	7440-22-4	0.24	15.3%	3307
	Ni	7440-02-0	0.003	0.2%	43
TOTAL			1.6		
Total weight			73		

Remark: Total weight range $\pm 10\%$

*) Lead in high melting temperature type solder acc. RoHS exempted

**) N. D. = not detected

Reflow Soldering acc. J-STD-020D

Material Analyses Reports available on request